

AMENDMENTS TO THE SPECIFICATION:

Please delete the word "Specification" at page 1, line 1.

Please amend the title of the invention, which is shown on page 1, lines 3 and 4,  
and on page 21, lines 3 and 4, as follows:

~~ELECTRONIC COMPONENT COMPRISING A MULTILAYER SUBSTRATE AND  
CORRESPONDING METHOD OF PRODUCTION~~

Please add the following centered heading at page 1, line 5:

TECHNICAL FIELD

Please add the following centered heading at page 1, line 9:

BACKGROUND

Please add the following centered heading at page 4, line 6:

SUMMARY

Please add the following centered heading at page 7, line 14:

DESCRIPTION OF THE DRAWINGS

Please add the following centered heading at page 7, line 20:

DETAILED DESCRIPTION

Applicant : Andreas Przada  
Serial No. : Not Yet Assigned  
Filed : Herewith  
Page : 3

Attorney's Docket No.: 14219-075US1  
Client's Ref.: P2002,0539USN

Please replace the Abstract on page 21 with the following new Abstract:

An electronic component includes a multi-layer substrate having an upper side and under side, and at least one integrated impedance converter. The electronic component also includes at least one chip component having external contacts. The at least one chip component is disposed on the upper side of the multi-layer substrate, and is electrically connected to the at least one integrated impedance converter.

Please delete the phrase "Figure 1" at page 21, line 16.